LATW2013

14th IEEE Latin-American Test Workshop

Cordoba, Argentina, April 2nd - 5th, 2013



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R. Velazco - TIMA, France raoul.velazco@imag.fr Y. Zorian – SYNOPSIS, USA Yervant.Zorian@synopsys.com

Leticia Bolzani Poehls - PUCRS, Brazil leticia@poehls.com Matteo Sonza Reorda - POLITO, Italy

matteo.sonzareorda@polito.it

Past General Cha Victor Champac - INAOE, Mexico

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CALL FOR PAPERS

The IEEE Latin-American Test Workshop (LATW) provides an annual forum for test and fault tolerance professionals and technologists from all over the world and in particular from Latin America to present and discuss various aspects of system, board, and component testing and fault-tolerance with design, manufacturing and field considerations in mind. Presented papers are also published in the IEEE Xplore Digital Library. The best papers of the 14th IEEE LATW will be invited to re-submit to the IEEE Design and Test of Computers, Journal of Electronic Testing: Theory and Applications (JETTA) and the Journal of Low Power Electronics (JOLPE).

Topics of interest include but are not limited to:

- Analog Mixed Signal Test
- Automatic Test Generation
- Built-In Self-Test
- Defect-Based Test
- Design and Synthesis for Testability
- Design for Reliable Embedded Software
- Design Verification/Validation
- Design for Electromagnetic Compatibility
- Fault Analysis and Diagnosis
- Fault Modeling and Simulation
- Fault-Tolerance in HW/SW
- Fault-Tolerant Architectures
- Memory Test and Repair
- On-Line Testing
- Process Control and Measurements
- Radiation/EMI
- Hardening Techniques
- Software Fault-Tolerance
- Software On-Line Testing
- System-on-Chip Test
- Test Resource Partitioning
- Yield Optimization

Paper Submission Information:

To encourage and facilitate discussions, participation will be limited. Those interested in presenting recent results at the workshop are invited to submit an extended abstract, one to three pages long, or a full length paper. PDF electronic submissions should be done via the workshop webpage: www.latw. tttc-events.org

Authors should send papers in the IEEE format. Detailed instructions are available at the workshop webpage. The Program Committee also welcomes proposals for panels and special topic sessions.

For additional information, please contact one of the Program Chairs:

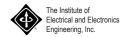
Letícia Maria Bolzani Poehls, Catholic University of Rio Grande do Sul (PUCRS), Brazil: leticia@poehls.com Matteo Sonza Reorda, Politecnico di Torino (POLITO), Italy: matteo.sonzareorda@polito.it

Submission Deadline: November 26th, 2012. Notification of Acceptance: December 31st, 2012.

Camera Ready: February 4th, 2013.

LATW 2013 will take place in Cordoba, called the Heartland of Argentina for its location near the geographical center of the country. The National University of Cordoba is one of the oldest universities in America and the oldest in Argentina. Cordoba has a strong colonial history combined with interesting native heritage and wonderful urban and natural sites that make it a privilege place for tourism. It has a lot of historical monuments that were declared Heritage of all Humanity by UNESCO. All others touristic places in Argentina, such as the Cataratas del Iguazú, Mendoza, Calafate, Patagonia, can be very easily reached from Cordoba, by plane or any other type of transportation due to its strategic location. The aeronautic and aerospace activities are also centered in Cordoba, together with several international software and electronic industries that are continuously established there, due to the large scientific and technologic heritage, human resources and facilities available in this wonderful place.

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